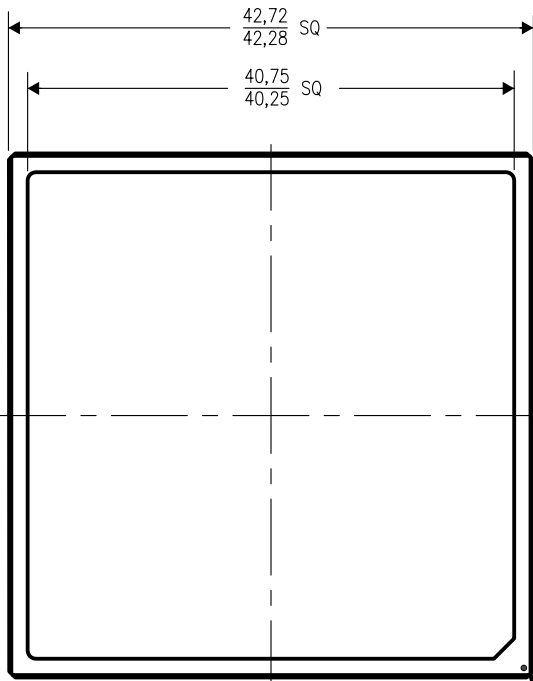


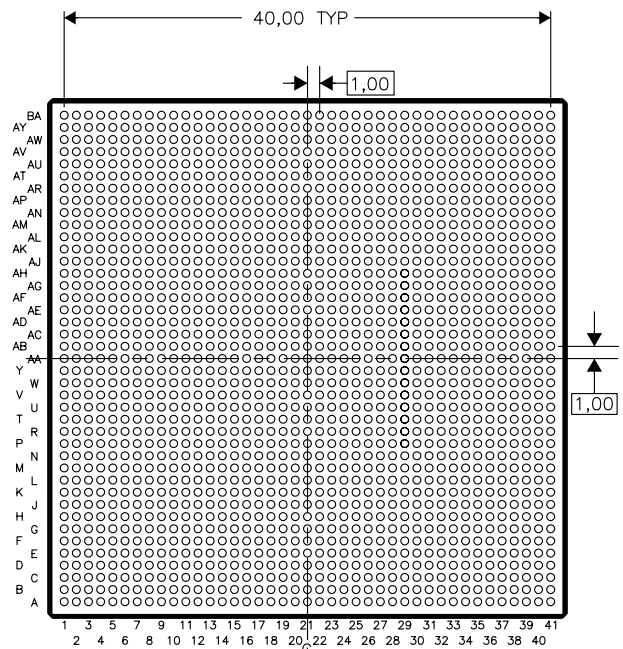
MECHANICAL DATA

GTJ (S-CBGA-N1681)

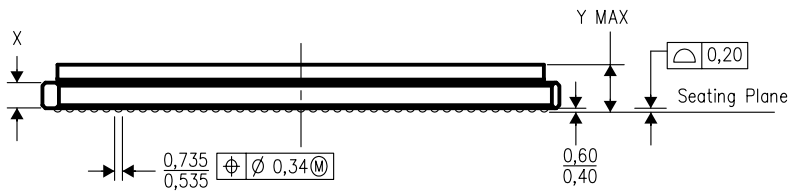
CERAMIC BALL GRID ARRAY



PIN A1 CORNER



BOTTOM VIEW



DIM	THICKNESS	
	A	B
X MAX	2,20	1,76
X MIN	1,80	1,44
Y	4,50	4,10

4205014-4/D 01/04

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Thermally enhanced ceramic package with a heat slug (HSL).
 - D. Flip chip application only.

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